

**WHAT IS CLAIMED IS:**

1. An integrated circuit package having central leads comprising:

5 a substrate having an upper surface, a lower surface, and a long slot penetrating from the upper to the lower surface, the lower surface forming with wiring regions arranged at the two sides of the long slot, and the wiring regions forming with a plurality of connected points, the length of the wiring regions are smaller than long slot of the substrate ;

a resistant layer<sup>42</sup> is coated on the lower surface<sup>54</sup> of the substrate<sup>40</sup>, and is located between the long slot<sup>56</sup> and wiring region<sup>58</sup>

10 a glue layer being coated on the upper surface of the substrate and being located at the periphery of the long slot ;

an integrated circuit having a first surface forming with a plurality of bonding pads and a second surface, the first surface being adhered to the glue layer, then the bonding pads being exposed from the long slot of the substrate ;

15 a plurality of wires, each of which is arranged within the long slot of the substrate and is electrically connected the bonding pad of the integrated circuit to the connected point of the substrate ; and

a first compound layer being filled within the long slot of the substrate for protecting the each wire.

20 2. The integrate circuit package having central leads according to claim 1,

wherein the length of the wiring regions are shorter than the long slot of the substrate

3. The integrate circuit package having central leads according to claim 1,  
wherein the connected points of the lower surface of the substrate is formed with  
5 ball grid array (BGA).

4. The integrate circuit package having central leads according to claim 1,  
wherein further comprises a second compound layer, which is covered on the  
upper surface of the substrate.